## **DB2U316**

### Silicon epitaxial planar type

For small current rectification DB27316 in USSMini2 type package

#### ■ Features

- ullet Low forward voltage  $V_F$
- Short reverse recovery time t<sub>rr</sub>
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

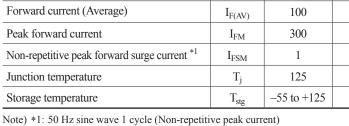
#### ■ Marking Symbol: 15

#### Packaging

DB2U31600L Embossed type (Thermo-compression sealing): 10 000 pcs / reel (standard)

#### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Reverse voltage	V <sub>R</sub>	30	V	
Maximum peak reverse voltage	V <sub>RM</sub>	30	V	
Forward current (Average)	I <sub>F(AV)</sub>	100	mA	
Peak forward current	$I_{FM}$	300	mA	
Non-repetitive peak forward surge current *1	I <sub>FSM</sub>	1	A	
Junction temperature	$T_j$	125	°C	
Storage temperature	T <sub>stg</sub>	-55 to +125	°C	



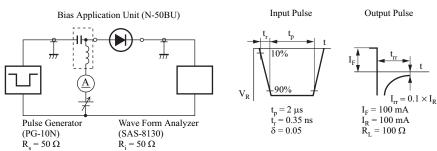
Unit: mm 0.6 0.13 85 0.2 0.38 1: Cathode 2: Anode Panasonic USSMini2-F2-B **JEITA** SC-116A SOD-923 Code

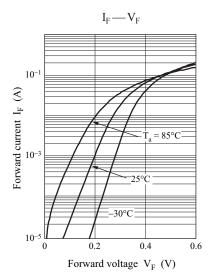
#### ■ Electrical Characteristics $T_a = 25$ °C±3°C

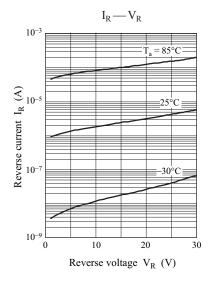
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	$V_{\mathrm{F}}$	$I_F = 100 \text{ mA}$			0.55	V
Reverse current	$I_R$	$V_R = 30 \text{ V}$			15	μΑ
Terminal capacitance	C <sub>t</sub>	$V_R = 10 \text{ V}, f = 1 \text{ MHz}$		2		pF
Reverse recovery time *1	t <sub>rr</sub>	$\begin{split} I_F &= I_R = 100 \text{ mA}, \ I_{rr} = 0.1 \times I_R \ , \\ R_L &= 100 \ \Omega \end{split}$		0.8		ns

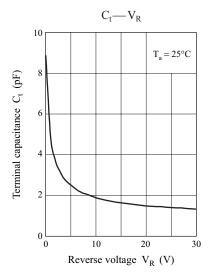
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

- 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
- 3. Absolute frequency of input and output is 250 MHz
- 4. \*1: t<sub>rr</sub> measurement circuit





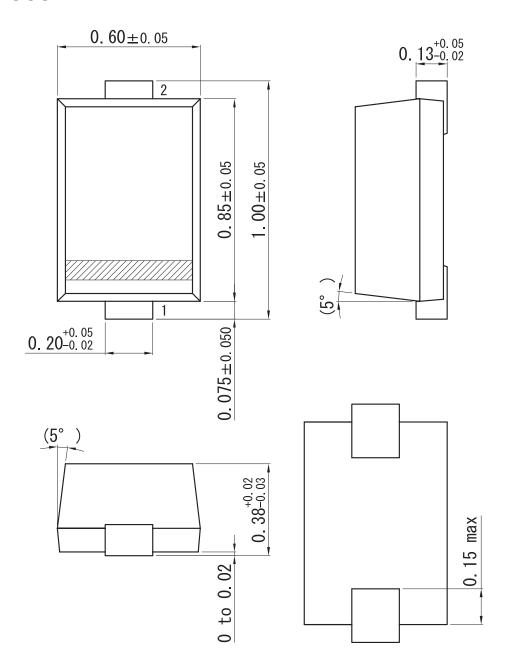




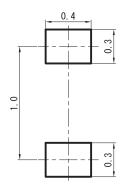
Ver. AED 2

### USSMini2-F2-B

Unit: mm



#### ■ Land Pattern (Reference) (Unit: mm)



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